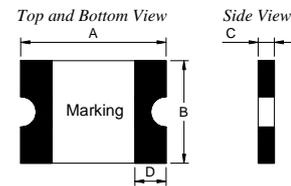


1、 Physical Dimensions(size of 1812)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
MSMD050/30	4.37	4.73	3.07	3.41	0.60	1.00	0.30	T050



2、 Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		Pd _{typ} (W)	R _{min} (Ω)	R1 _{max} (Ω)
					Current(A)	Time(S)			
MSMD050/30	0.50	1.00	30	40	8.0	0.15	0.8	0.15	1.00

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

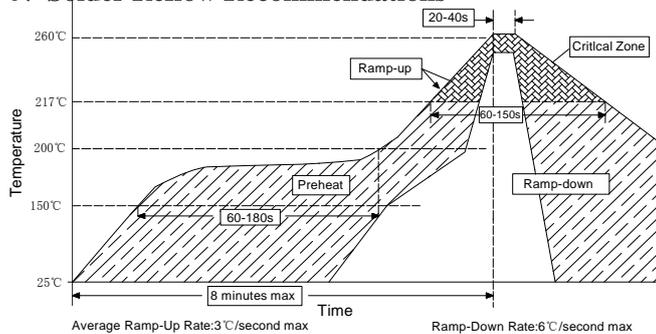
R1_{max}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

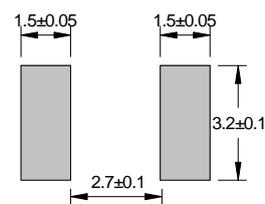
3、 Thermal Derating

MSMD050/30	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	0.77	0.68	0.59	0.50	0.44	0.40	0.37	0.33	0.29
Trip Current(A)	1.54	1.36	1.18	1.00	0.88	0.80	0.74	0.66	0.58

4、 Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、 Package Information

Packing quantity: 2000PCS/Reel

Note: Reel packaging per EIA-481-1 standard